IN THE CENTED STATES PATENT AND TRAD ARK OFFICE

DT01 Rec'd PCT/PT0 15 OCT 2004

Applicant(s):

Leib and Mund

Serial No.:

Not Yet Assigned

Filed:

Herewith

For:

PROCESS FOR FORMING A HOUSING FOR ELECTRONIC MODULES, AND ELECTRONIC MODULES ECAPSULATED IN

THIS WAY

Art Unit:

Not Yet Assigned

Examiner:

Not Yet Assigned

Confirmation No.:

Not Yet Assigned

Customer No.:

27623

Attorney Docket No.:

2133.063USU

Date: October 15, 2004

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

In accordance with applicants' duty of disclosure under 37 C.F.R. §1.56, we are enclosing form PTO-1449 listing information that may be material to the patentability of this application.

It should be understood that attention has been called to the citations that have been deemed to be pertinent to the claimed present invention. In concluding what was pertinent, the criteria employed was considered most appropriate in light of the invention shown in the present application. However, the Examiner or others may deem some other criteria to be just as appropriate or more appropriate. Therefore, the Examiner is respectfully urged to review the listed citations and to make the usual DT01 Rec'd PCT/PT0 1 5 OCT 2004 careful independent search for other prior art that may be pertinent.

Since this Information Disclosure Statement is being filed herewith the filing date of this application, no petition or fee is required.

Applicants respectfully request favorable consideration and that this application be passed to allowance.

Respectfully submitted,

Charles N. J. Ruggiero

Reg. No. 28,468

Attorney for Applicant(s)

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Stamford, CT 06901-2682

(203) 327-4500

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| citation if not in conformance and not considered. Include copy of this form with next communication to the applicant. | | | | | | | | | | |